

Schottky Barrier Diode Silicon Epitaxial

CUS15S40

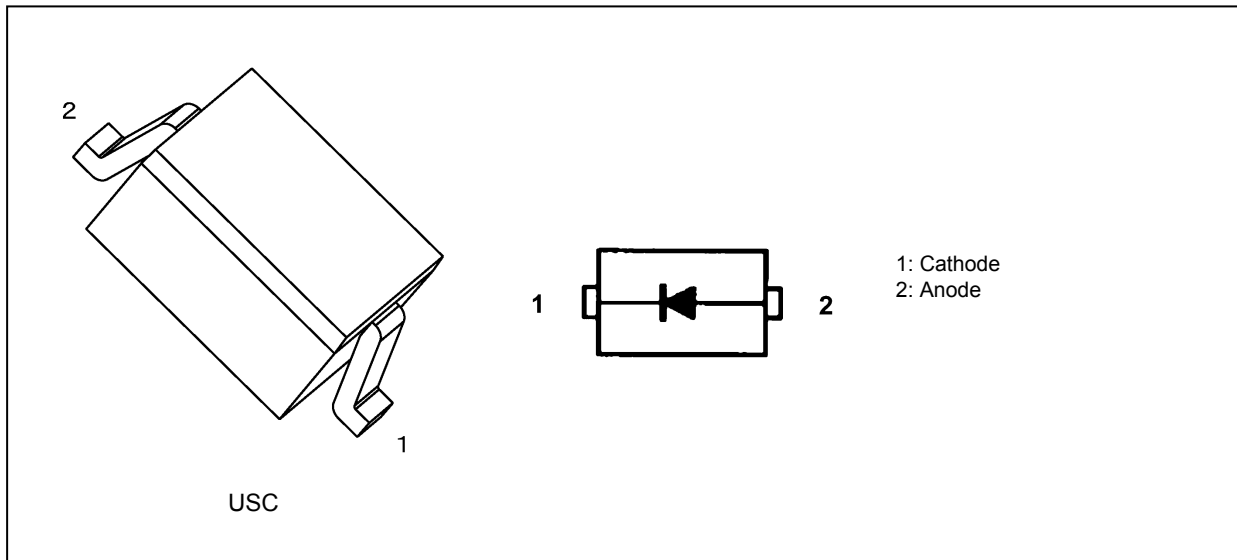
1. Applications

- High-Speed Switching

2. Features

- (1) Small package
- (2) Low forward voltage: $V_F(2) = 0.47 \text{ V (typ.)}$

3. Packaging and Internal Circuit



Start of commercial production

2013-10

4. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Rating	Unit
Peak reverse voltage	V_{RM}		40	V
Average rectified current	I_O	(Note 1)	1.5	A
Non-repetitive peak forward surge current	I_{FSM}	(Note 2)	5	A
Junction temperature	T_j		125	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to 125	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on an FR4 board.

(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 645 mm²)

Note 2: Measured with a 10 ms pulse.

5. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward voltage	$V_F(1)$	$I_F = 1\text{ A}$ (Pulse test)	—	0.40	0.45	V
Forward voltage	$V_F(2)$	$I_F = 1.5\text{ A}$ (Pulse test)	—	0.47	0.55	V
Reverse current	I_R	$V_R = 40\text{ V}$ (Pulse test)	—	—	200	μA
Total capacitance	C_t	$V_R = 0\text{ V}$, $f = 1\text{ MHz}$	—	170	—	pF

6. Marking

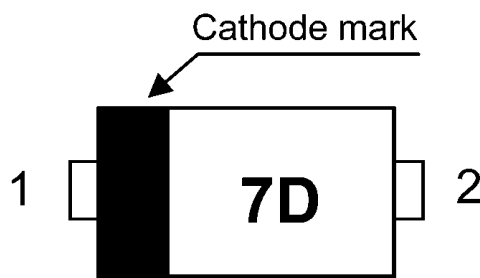
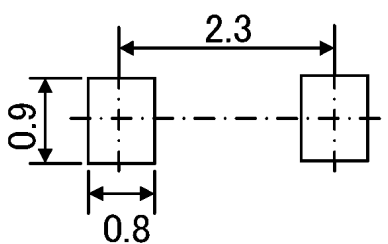


Fig. 6.1 Marking

Marking Code	Part Number
7D	CUS15S40

7. Usage Considerations

- Schottky barrier diodes (SBDs) have reverse leakage greater than other types of diodes. This makes SBDs more susceptible to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.

8. Land Pattern Dimensions (for reference only)**Fig. 8.1 Land Pattern Dimensions for Reference Only (Unit: mm)**

9. Characteristics Curves (Note)

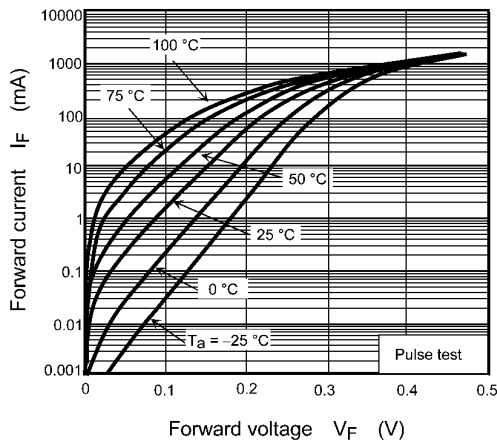


Fig. 9.1 $I_F - V_F$

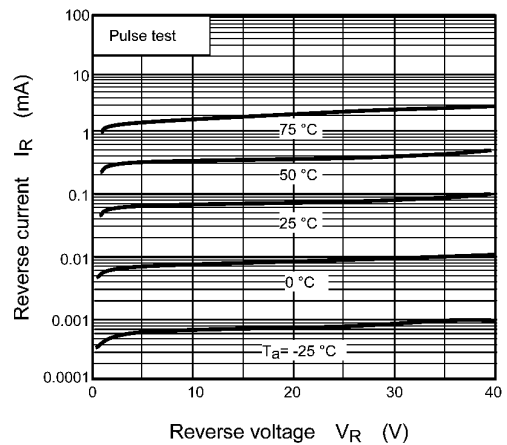


Fig. 9.2 $I_R - V_R$

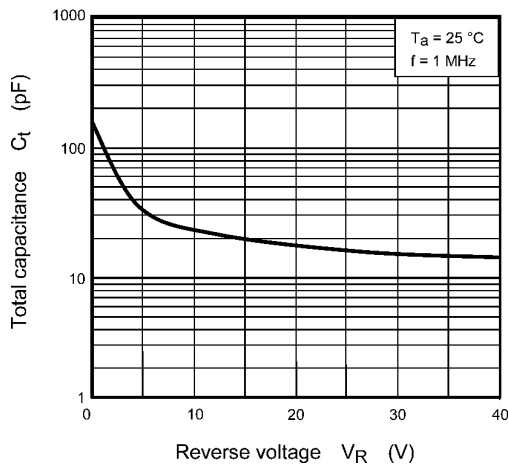


Fig. 9.3 $C_t - V_R$

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

Package Dimensions

Unit: mm



Weight: 4.5 mg (typ.)

Package Name(s)
Nickname: USC

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